

MOSFET – N-Channel, UniFET™

200 V, 39 A, 66 m Ω

FDP39N20, FDPF39N20

Description

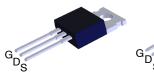
UniFET $^{\text{m}}$ MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on–state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

Features

- $R_{DS(on)} = 66 \text{ m}\Omega \text{ (Max.)} @ V_{GS} = 10 \text{ V}, I_D = 19.5 \text{ A}$
- Low Gate Charge (Typ. 38 nC)
- Low C_{rss} (Typ. 57 pF)
- 100% Avalanche Tested

Applications

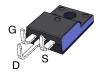
- PDP TV
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply





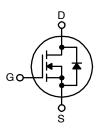
TO-220-3LD CASE 340AT

TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT

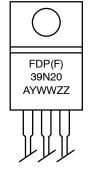


TO-220 FULLPAK 3LD L-FORMED CASE 340BM

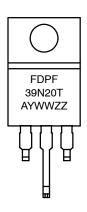
N-CHANNEL MOSFET



MARKING DIAGRAMS



1



FDP(F)39N20(T) = Specific Device Code A = Assembly Location

YWW = Date Code (Year and Week)

ZZ = Assembly Lot

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 9 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Symbol	Parameter		FDP39N20	FDPF39N20 / FDPF39N20TLDTU	Unit
V _{DSS}	Drain-Source Voltage		200	200	٧
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	39 23.4	39* 23.4*	A A
I _{DM}	Drain Current	- Pulsed (Note 1)	156	156*	Α
V _{GSS}	Gate-Source Voltage		±30	±30	٧
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		860	860	mJ
I _{AR}	Avalanche Current (Note 1)		39	39	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		25.1	25.1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	4.5	V/ns
P _D	Power Dissipation	(T _C = 25°C) – Derate Above 25°C	251 2.0	37 0.29	W W/°C
$T_{J_i} T_{STG}$	Operating and Storage Temperature Range		-55 to +150	-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	FDP39N20	FDPF39N20 / FDPF39N20TLDTU	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.5	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
OFF CHAR	ACTERISTICS					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200	-	_	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	0.2	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V V _{DS} = 160 V, T _C = 125°C	- -	- -	1 10	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{V}$	-	-	-100	nA
ON CHARA	ACTERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 19.5 A	-	0.056	0.066	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 19.5 A	-	28.5	-	S
DYNAMIC	CHARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	-	1640	2130	pF
C _{oss}	Output Capacitance	1	-	400	520	pF
C_{rss}	Reverse Transfer Capacitance	1	_	57	85	pF

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)(continued)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
SWITCHIN	G CHARACTERISTICS	•				
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 100 \text{ V}, I_D = 39 \text{ A},$	-	30	70	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_G = 25 \Omega \text{ (Note 4)}$	-	160	330	ns
t _{d(off)}	Turn-Off Delay Time		-	150	310	ns
t _f	Turn-Off Fall Time		-	150	310	ns
Qg	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_D = 39 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 4)	-	38	49	nC
Q_{gs}	Gate-Source Charge		-	11	-	nC
Q_{gd}	Gate-Drain Charge		_	16.5	-	nC
RAIN-SC	OURCE DIODE CHARACTERISTICS AND M	AXIMUM RATINGS				
I _S	Maximum Continuous Drain-Source Diode Forward Current		-	-	39	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	156	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 39 A	-	_	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 39 A,	-	152	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	_	1.1	-	μC

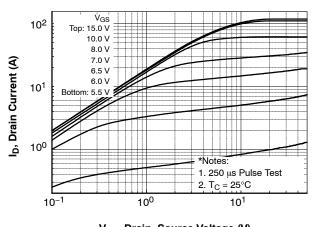
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. L = 0.85 mH, $I_{AS} = 39$ A, $V_{DD} = 50$ V, $R_{G} = 25$ Ω , starting $T_{J} = 25^{\circ}C$.

3. $I_{SD} \le 39$ A, $I_{SD} \le 39$ A, $I_{SD} \le 80$ A, $I_{SD} \le 80$ A, starting $I_{SD} \le 80$ A, and $I_{SD} \le 80$ A, di/dt $I_$

TYPICAL PERFORMANCE CHARACTERISTICS



V_{DS}, Drain-Source Voltage (V)

Figure 1. On-Region Characteristics

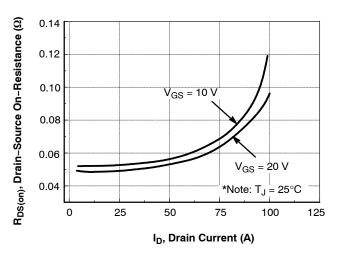


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

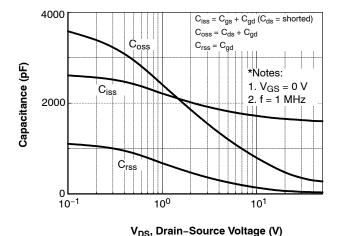
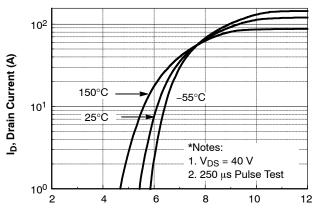


Figure 5. Capacitance Characteristics



V_{GS}, Gate-Source Voltage (V)

Figure 2. Transfer Characteristics

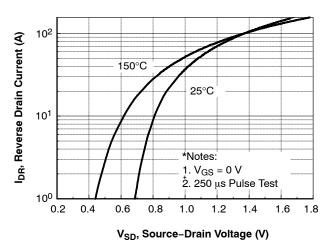
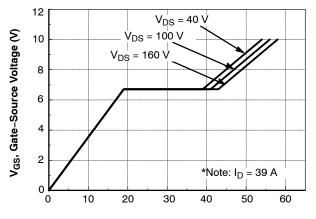


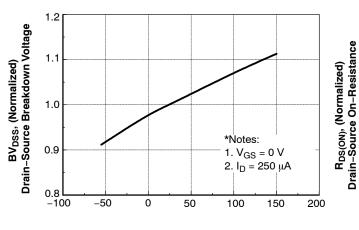
Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



Q_G, Total Gate Charge (nC)

Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)



3.0 2.5 2.0 1.5 1.0 -100 -50 0 50 100 150 200

T_J, Junction Temperature (°C)

Figure 7. Breakdown Voltage Variation vs. Temperature

T_J, Junction Temperature (°C)

100 us

Figure 8. On–Resistance Variation vs. Temperature

10 ms

100 ms

DC

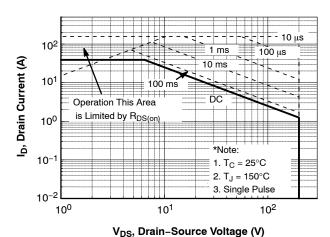
*Note:

1. $T_C = 25^{\circ}C$

2. T_J = 150°C

3. Single Pulse

10²



I_D, Drain Current (A)

10²

10¹

10⁰

 10^{-1}

10⁻² 10⁰

Operation This

Area is Limited by

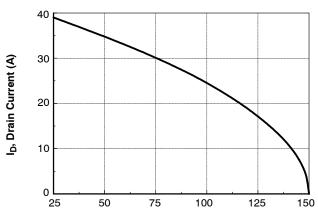
V_{DS}, Drain-Source Voltage (V)

10¹

Figure 9. Maximum Safe Operating Area – FDP39N20

Figure 10. Maximum Safe Operating Area –

FDPF39N20



T_C, Case Temperature (°C)

Figure 11. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

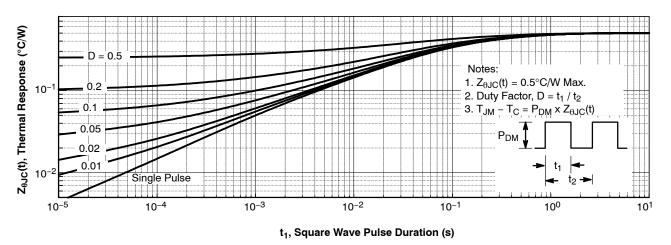


Figure 12. Transient Thermal Response Curve - FDP39N20

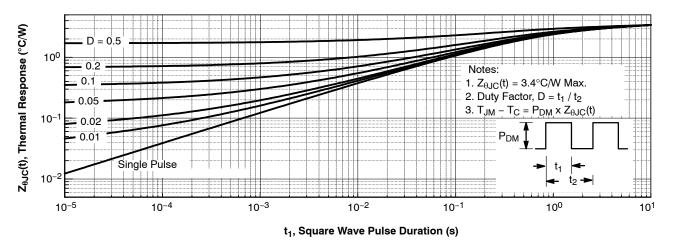


Figure 13. Transient Thermal Response Curve - FDPF39N20

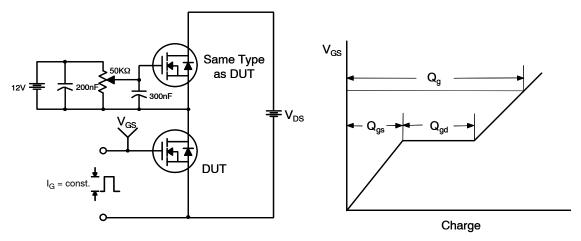


Figure 14. Gate Charge Test Circuit & Waveform

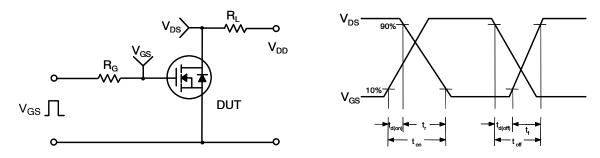


Figure 15. Resistive Switching Test Circuit & Waveforms

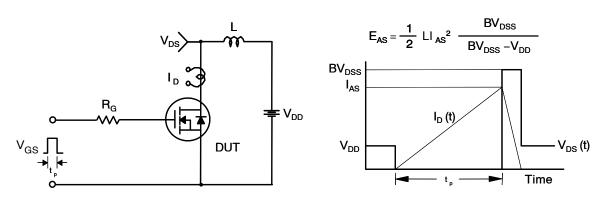
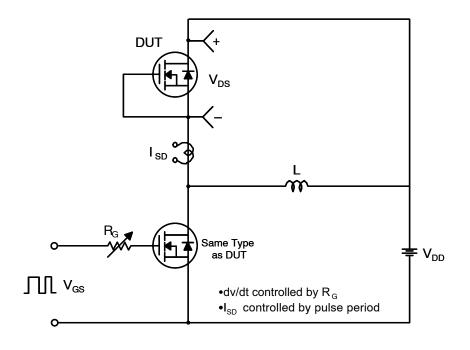


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms



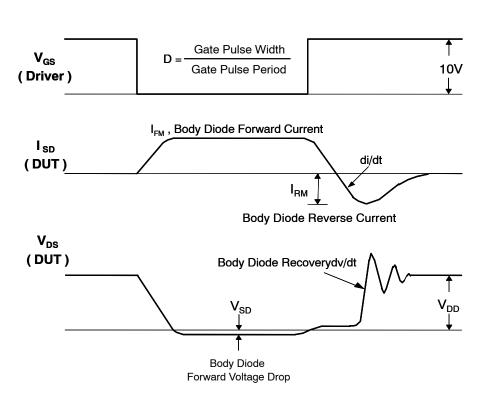


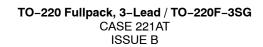
Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

ORDERING INFORMATION

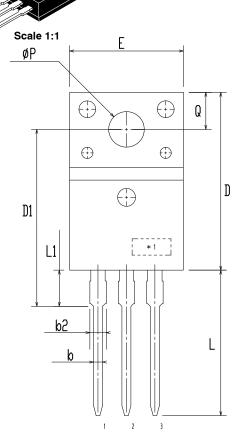
Device	Device Marking	Package	Shipping
FDP39N20	FDP39N20	TO-220	1000 Units / Tube
FDPF39N20	FDPF39N20	TO-220F	1000 Units / Tube
FDPF39N20TLDTU	FDPF39N20T	TO-220F (L-formed)	800 Units / Tube

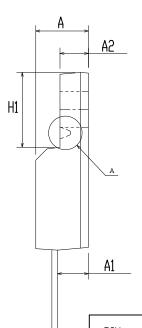
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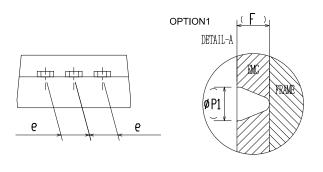




DATE 19 JAN 2021







DIM	LITE	LIUI I LNO	
ויונע	MIN	NDM	MAX
Α	4.50	4.70	4.90
A1	2.56	2.76	2.96
A2	2.34	2.54	2.74
b	0.70	0.80	0.90
b2	~	2	1.47
С	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.60	15.80	16.00
E	9.96	10.16	10.36
е	2.34	2.54	2.74
F	~	0.84	~
H1	6.48	6.68	6.88
L	12.78	12.98	13.18
L1	3.03	3.23	3.43
ØΡ	2.98	3.18	3.38
ø P1	~	1.00	~
Q	3.20	3.30	3.40

MILLIMITERS

NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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TO-220-3LD CASE 340AT ISSUE B

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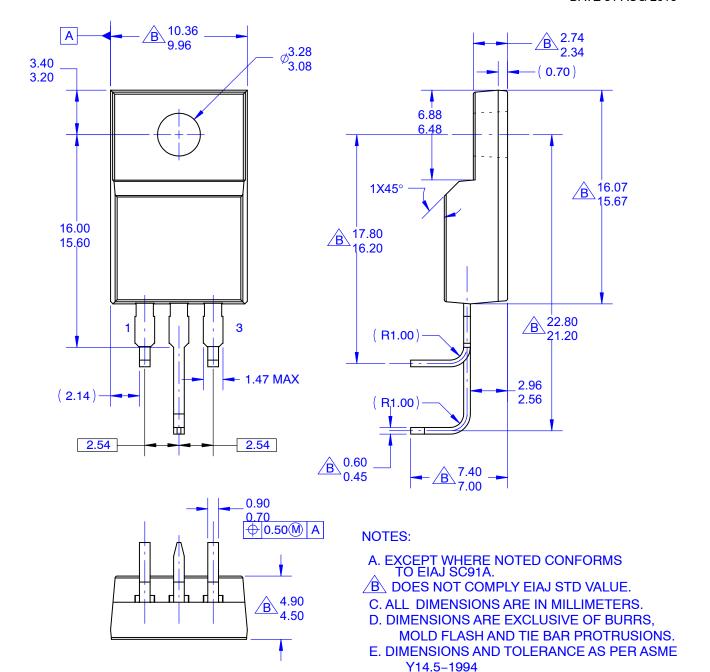
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